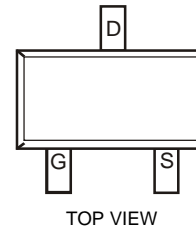
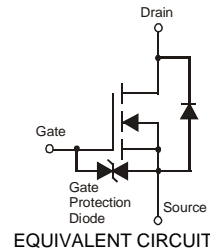


Features

- Low On-Resistance:
 - 3.0 Ω @ 4.5V
 - 4.0 Ω @ 2.5V
 - 6.0 Ω @ 1.8V
 - 10 Ω @ 1.5V
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- ESD Protected Gate
- Lead, Halogen, and Antimony Free By Design/RoHS Compliant (Note 2)**
- "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT-523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.002 grams (approximate)



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V _{DSS}	20	V
Gate-Source Voltage	V _{GSS}	±10	V
Drain Current (Note 1)	I _D	230	mA
Pulsed Drain Current T _P = 10μs	I _{DM}	805	mA

Thermal Characteristics @T_A = 25°C unless otherwise specified

Total Power Dissipation (Note 1)	P _D	300	mW
Thermal Resistance, Junction to Ambient (Note 1)	R _{θJA}	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 - No purposefully added lead.
 - Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	—	—	V	V _{GS} = 0V, I _D = 100μA
Zero Gate Voltage Drain Current @ T _C = 25°C	I _{DSS}	—	—	500	nA	V _{DS} = 20V, V _{GS} = 0V
Gate-Body Leakage	I _{GSS}	—	—	±1 ±500 ±100	μA nA nA	V _{GS} = ±10V, V _{DS} = 0V V _{GS} = ±8V, V _{DS} = 0V V _{GS} = ±5V, V _{DS} = 0V
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	V _{GS(th)}	0.5	—	1.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS (ON)}	— — — — —	1.8 2.4 2.9 3.7 5.4	3.0 4.0 6.0 10.0 15.0	Ω	V _{GS} = 4.5V, I _D = 100mA V _{GS} = 2.5V, I _D = 50mA V _{GS} = 1.8V, I _D = 20mA V _{GS} = 1.5V, I _D = 10mA V _{GS} = 1.2V, I _D = 1mA
Forward Transconductance	Y _{fs}	—	242	—	mS	V _{DS} =10V, I _D = 0.1A
Source-Drain Diode Forward Voltage	V _{SD}	0.5	—	1.0	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	—	14.1	—	pF	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	2.9	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	1.6	—	pF	
SWITCHING CHARACTERISTICS, V _{GS} = 4.5V (Note 5)						
Turn-On Delay Time	t _{d(on)}	—	3.8	—	ns	V _{GS} = 4.5V, V _{DD} = 10V I _D = 200mA, R _G = 2.0Ω
Rise Time	t _r	—	7.9	—		
Turn-Off Delay Time	t _{d(off)}	—	13.4	—		
Fall Time	t _f	—	15.2	—		

- Notes: 4. Short duration pulse test used to minimize self-heating effect.
5. Switching characteristics are independent of operating junction temperature.

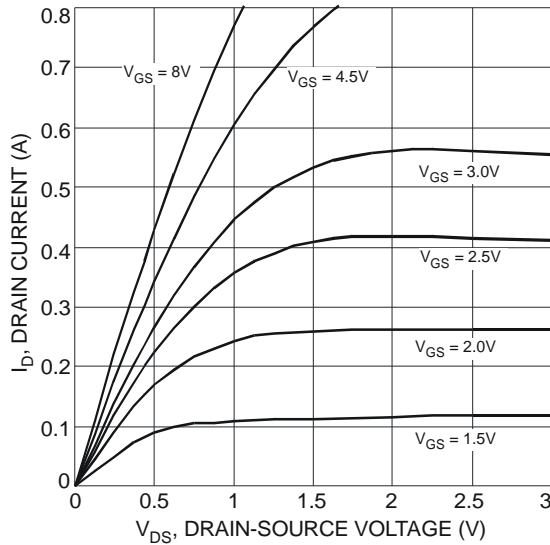


Fig. 1 Typical Output Characteristic

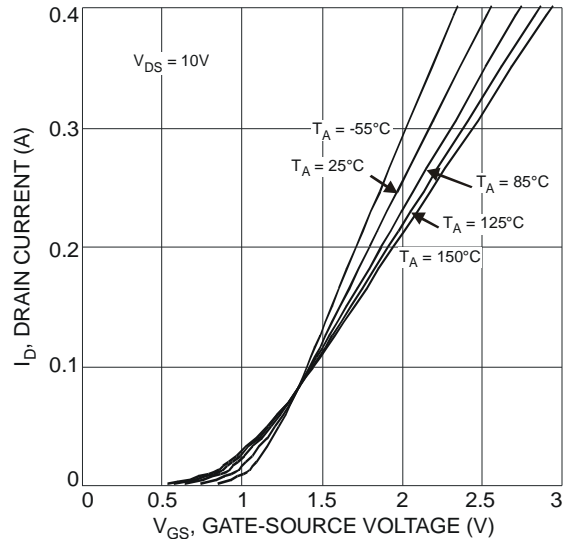


Fig. 2 Typical Transfer Characteristic

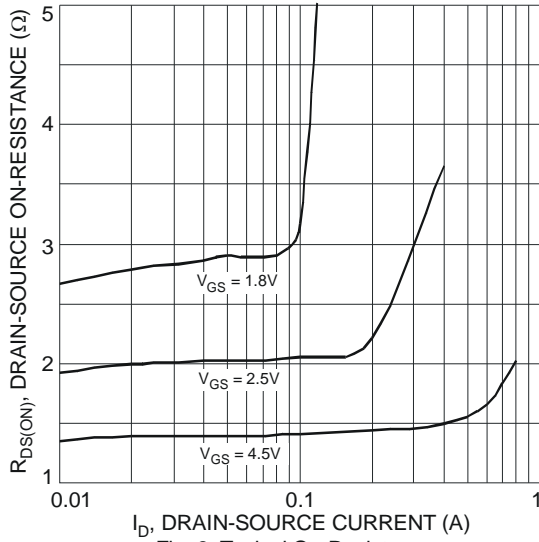


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

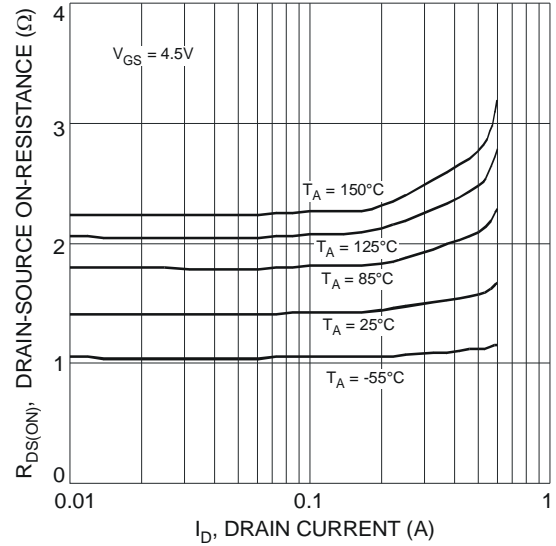


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

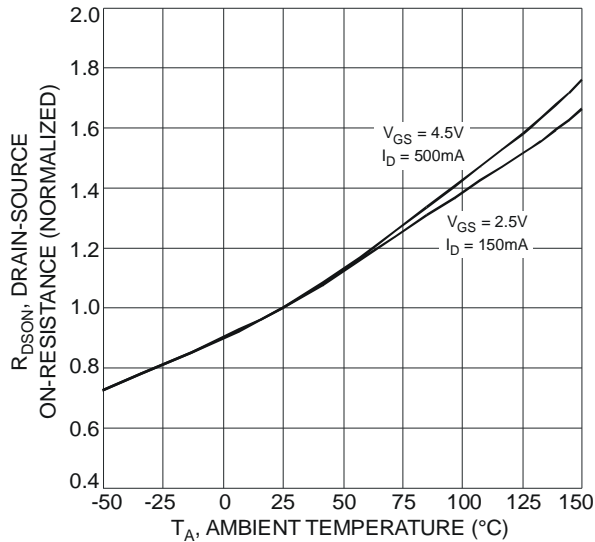


Fig. 5 On-Resistance Variation with Temperature

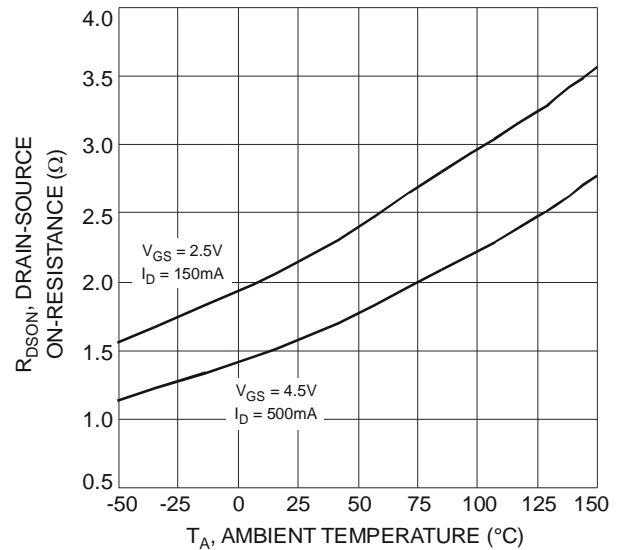


Fig. 6 On-Resistance Variation with Temperature

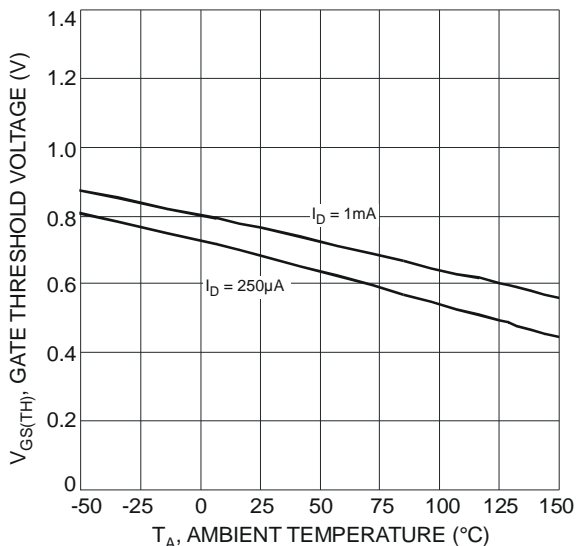


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

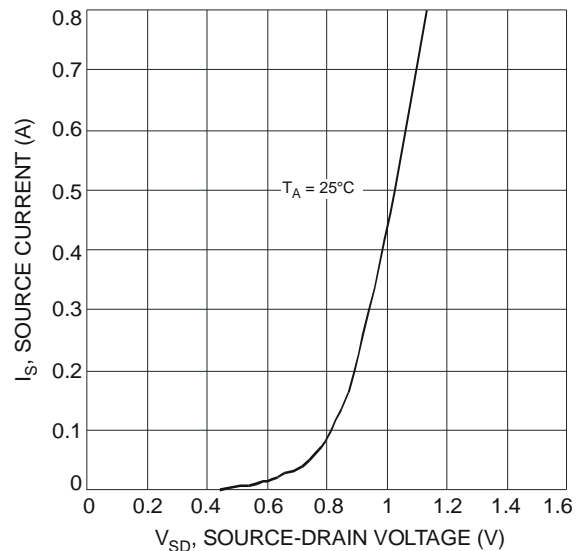
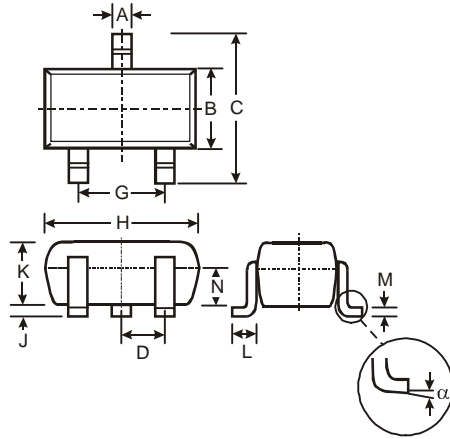


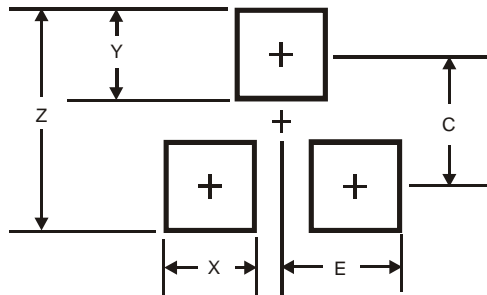
Fig. 8 Diode Forward Voltage vs. Current

Package Outline Dimensions



SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7

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